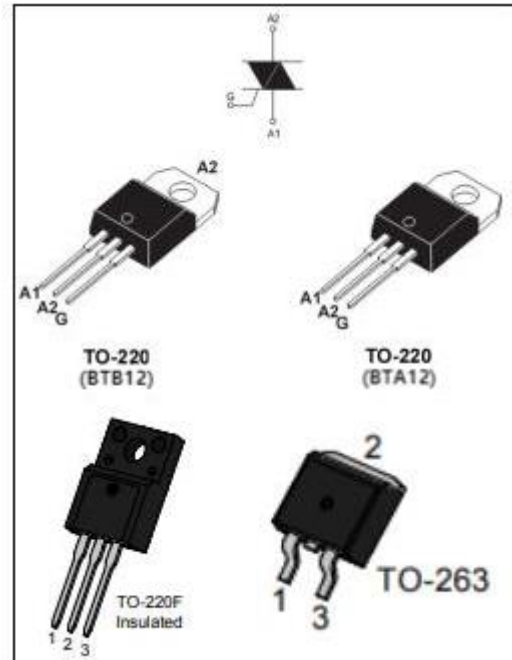


●Product features and main applications:

NPNPN five-layer structure of silicon bidirectional devices; with independent intellectual property rights of single-sided digging technology, table glass passivation process; multi-layer metallized electrodes on the back; with high blocking voltage and high temperature stability.

Mainly used in:

vacuum cleaners, power tools and other motor speed controllers; solid state relays; heating controllers (temperature regulation); other phase control circuits.



●Characteristics

Table 1. Absolute maximum ratings ($T_j = 25^\circ\text{C}$ unless otherwise stated)

Symbol	Parameter name			value	Unit
$I_{T(RMS)}$	RMS on-state current (full sine wave)	BTA BTB	$T_c=80^\circ\text{C}$ $T_c=90^\circ\text{C}$	12	A
I_{TSM}	Non repetitive surge peak on-state current (full cycle, T_j initial = 25°C)	$F=50\text{HZ}$ $t_p=20\text{ms}$		120	A
I^2t	I^2t value for fusing	$t_p=10\text{ms}$		72	A^2S
di/dt	Critical rate of rise of on-state current $I_G = 2 \times I_{GT}$, $t_r \leq 100\text{ ns}$	$T_j=125^\circ\text{C}$		50	A/us

V_{DRM}/V_{RRM}	Off state repetitive peak voltage Reverse repetitive peak voltage	$T_j=25^{\circ}\text{C}$		600/800/1000	V
I_{GM}	Peak gate current	$t_p=20\mu\text{s}$	$T_j=150^{\circ}\text{C}$	4	A
$P_{G(AV)}$	Average gate power dissipation		$T_j=150^{\circ}\text{C}$	1	W
T_{stg} T_j	Storage junction temperature range Operating junction temperature range			$-40\text{to}+150$ $-40\text{to}+125$	$^{\circ}\text{C}$

● **Table 2. Electrical characteristics ($T_j = 25^{\circ}\text{C}$, unless otherwise specified) -- 3 quadrants**

Symbol	Name and test conditions	Quadrant	Range	value	Unit
I _{GT}	V _D =12V R _L =100 Ω	I II III	MAX	≤ 50	mA
V _{GT}			MAX	1.5	V
V _{GD}	VD = VDRM, RL = 3.3 kΩ , Tj = 125 ° C		MIN	0.2	V
I _H	IT = 100 mA		MAX	60	mA
I _L	IG = 1.2 x IGT		MAX	60	mA
				100	
dv/dt	VD = 67% VDRM, gate open, Tj = 125 ° C		MIN	500	V/us
(dv/dt)c	Critical rise rate of commutation voltage TJ = 150 °C		MIN	8	V/us

●Table 3. Electrical characteristics ($T_j = 25\text{ }^{\circ}\text{C}$, unless otherwise specified) - Standard Triac (4 quadrants)

Symbol	Name and test conditions	Quadrant	Range	value		Unit
I _{GT}	V _D =12V R _L =100 Ω	I II III IV	MAX	I II III	IV	mA
				≦ 50	≦ 120	
V _{GT}			MAX	1.5		V
V _{GD}	VD = VDRM, RL = 3.3 kΩ , Tj = 125 ° C		MIN	0.2		V
I _H	I _T =500mA		MAX	60		mA
I _L	IG = 1.2 x IGT		MAX	60		mA
				100		
dv/dt	VD = 67% VDRM, gate open, Tj = 125 ° C		MIN	500		V/us
(dv/dt) _c	Critical rise rate of commutation voltage TJ = 150 °C		MIN	10		V/us

●Static parameters

Symbol	Parameter name			value	Unit
V_{TM}	$I_{TM}= 24A$	$T_j=25^{\circ}C$	MAX	1.50	V
V_{T0}	threshold on-state voltage	$T_j=150^{\circ}C$	MAX	0.86	V
R_d	Dynamic resistance	$T_j=150^{\circ}C$	MAX	36.6	m Ω
I_{DRM} I_{RRM}	$V_{DRM} = V_{RRM}$	$T_j=25^{\circ}C$	MAX	5	μA
		$T_j=150^{\circ}C$		1	mA
$R_{th(j-c)}$	Junction to ambient	BTA		2.05	$^{\circ}C/W$
		BTB		1.25	

●BT138-800 characteristic curve

FIG.1 Maximum power dissipation versus RMS on-state current

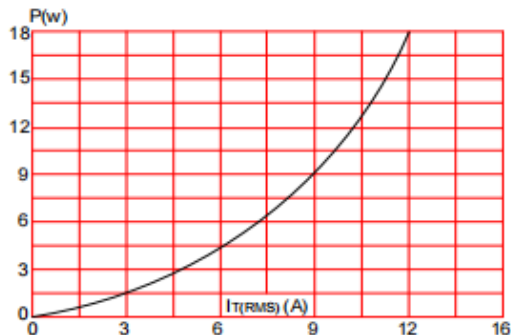


FIG.3: Surge peak on-state current versus number of cycles

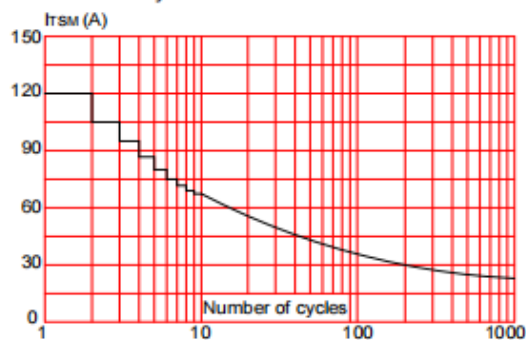


FIG.5: Non-repetitive surge peak on-state current for a sinusoidal pulse with width $t_p < 10\text{ms}$, and corresponding value of $I^2 t$ ($dI/dt < 50\text{A}/\mu\text{s}$)

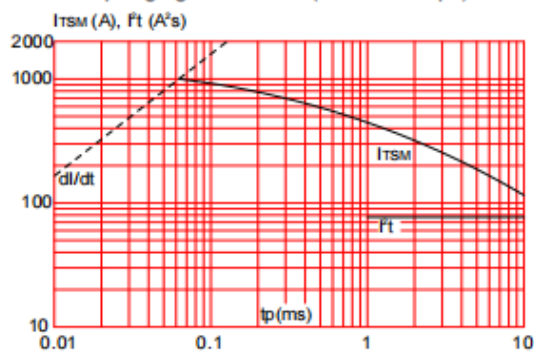


FIG.2: RMS on-state current versus case temperature

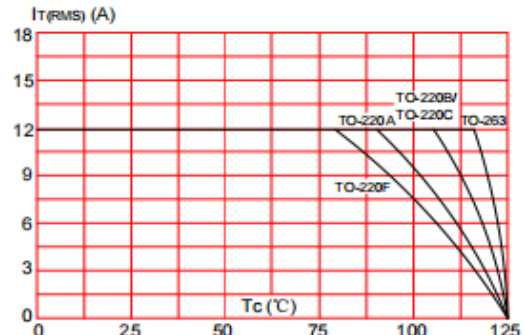


FIG.4: On-state characteristics (maximum values)

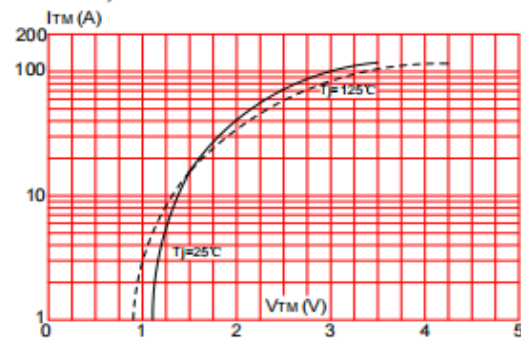
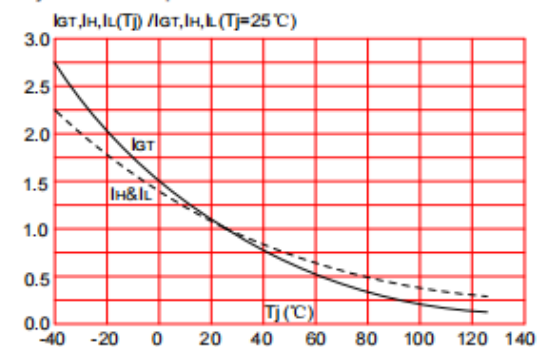
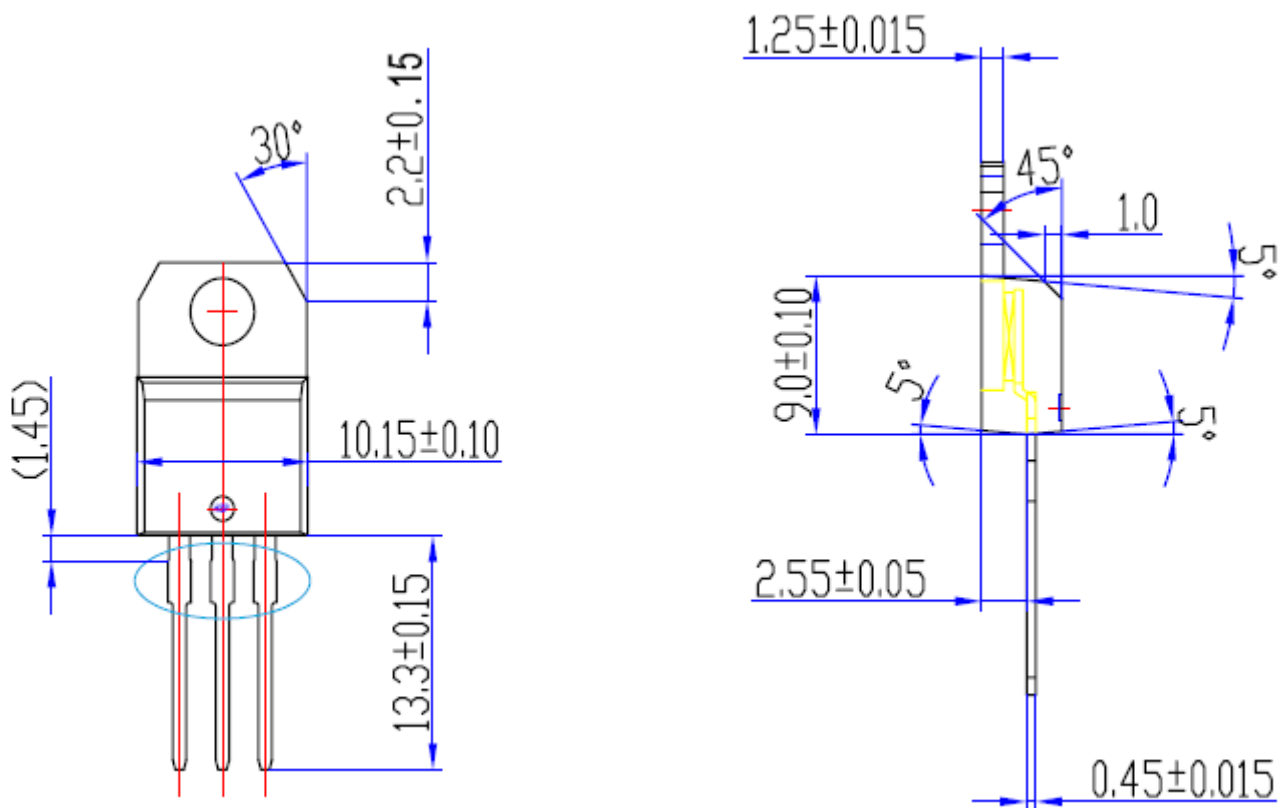


FIG.6: Relative variations of gate trigger current, holding current and latching current versus junction temperature



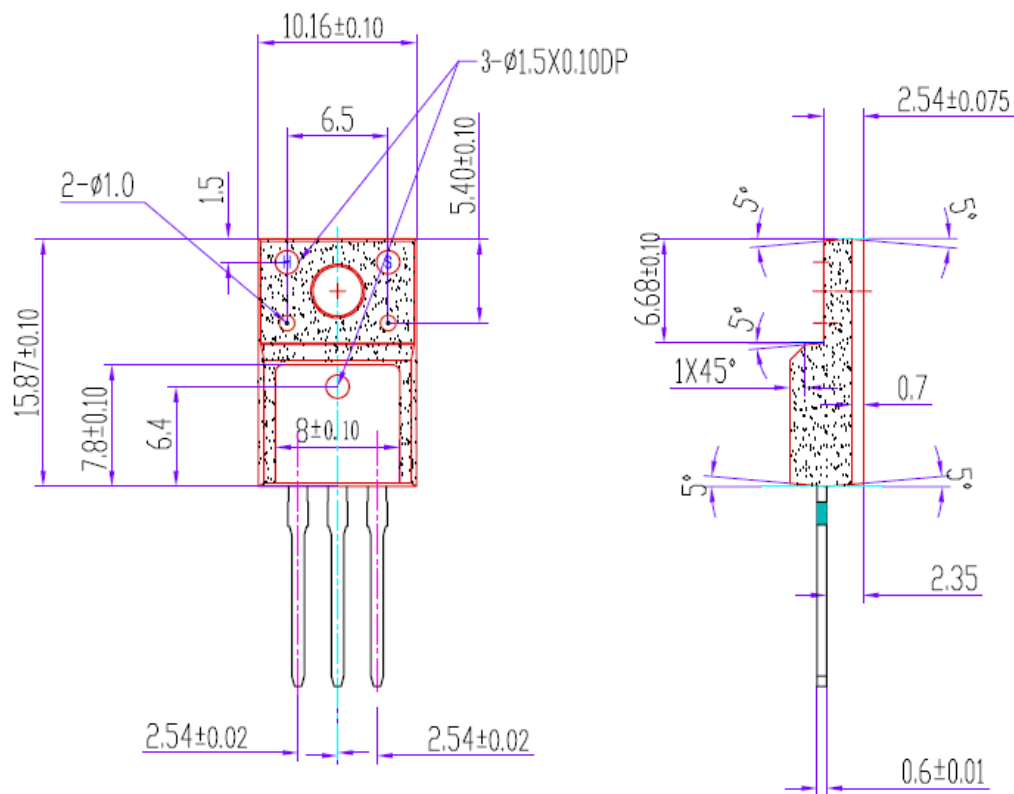
● TO-220 Dimensional drawing:

Unit: mm (± 0.1)



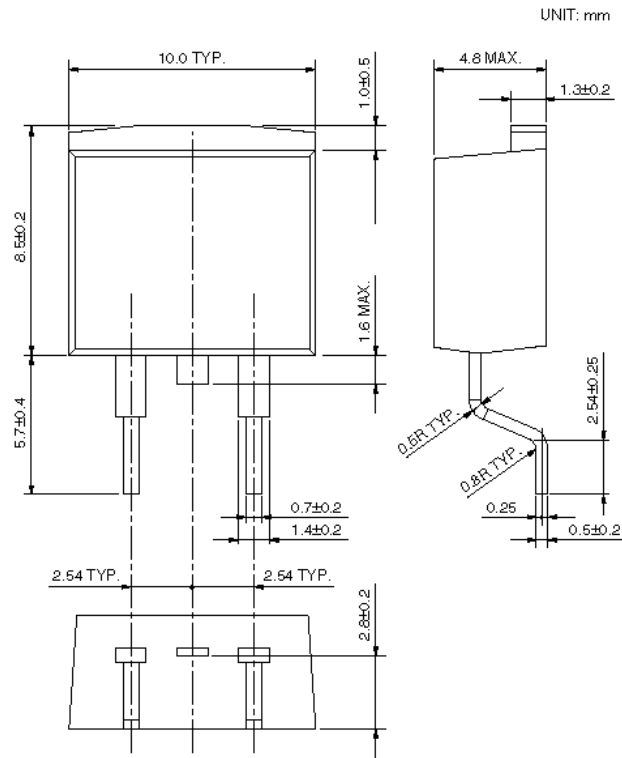
● TO-220F Dimensional drawing:

Unit: mm (± 0.1)



●TO-263 Dimensional drawing:

Unit: mm (± 0.1)



: The area without solder plated

